



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

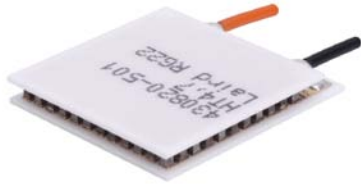
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The ThermaTEC™ Series of thermoelectric modules (TEMs) are designed to operate under cycling conditions or high temperature applications. This product line is available in multiple configurations and is ideal for applications that require both heating and cooling mode (reverse polarity) or power generation. Assembled with proprietary solder construction, Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics, the ThermaTEC Series is designed for higher current and larger heat-pumping applications.



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FEATURES

- Thermal cycling durability
- Power cycling reliability
- Precise temperature control
- Strong lead attachment
- RoHS compliant
- Continuous operation at high temperatures

APPLICATIONS

- Analytical instrumentation
- PCR cyclers
- Thermal test sockets
- Electronic enclosure cooling
- Chillers (liquid cooling)
- Power generation

PERFORMANCE SPECIFICATIONS

Hot Side Temperature (°C)	25°C	50°C
Qmax (Watts)	18.4	20.2
Delta Tmax (°C)	64	75
I _{max} (Amps)	3.8	3.8
V _{max} (Volts)	8.1	9.2
Module Resistance (Ohms)	1.95	2.20

SUFFIX	THICKNESS (PRIOR TO TINNING)	FLATNESS & PARALLELISM	HOT FACE	COLD FACE	LEAD LENGTH
11	0.161" ± 0.005"	0.002" / 0.0035"	Lapped	Lapped	6.0"
TA	0.161" ± 0.001"	0.001" / 0.001"	Lapped	Lapped	6.0"
TB	0.161" ± 0.0005"	0.0005" / 0.0005"	Lapped	Lapped	6.0"

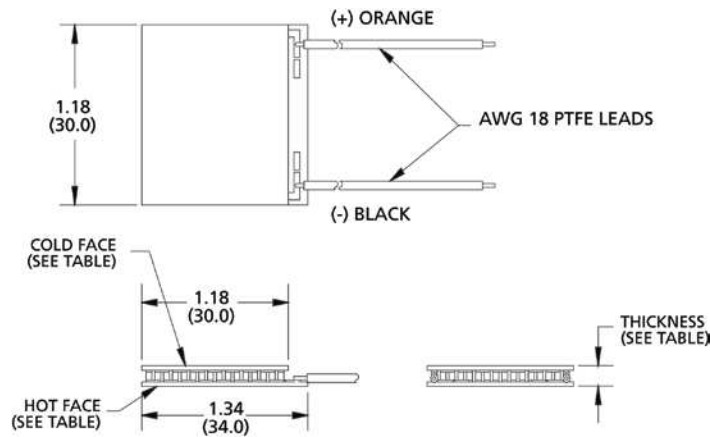
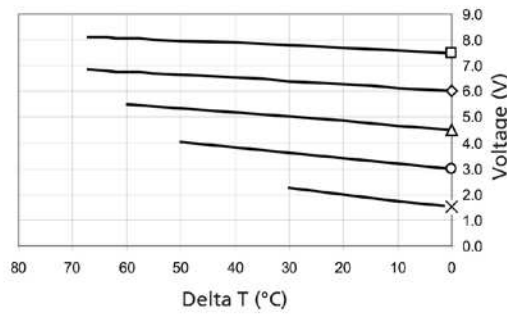
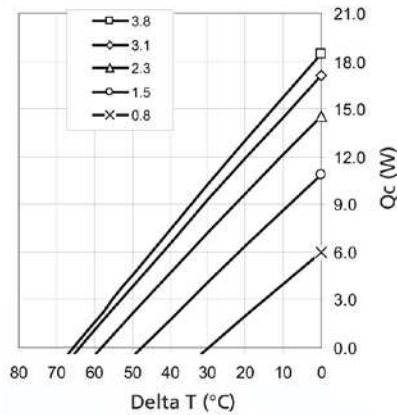
SEALING OPTION

SUFFIX	SEALANT	COLOR	TEMP RANGE	DESCRIPTION
R	RTV	White	-60 to 204°C	Non-corrosive, silicone adhesive sealant
E	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

Performance Curves at Th = 25°C

THERMO

ELECTRIC



Ceramic Material: Alumina (Al₂O₃)
 Solder Construction: 271°C, Proprietary

OPERATING TIPS

- Max operating temperature: 175°C
- Do not exceed I_{max} or V_{max} when operating module
- Reference assembly guidelines for recommended installation

LAIRD-ETS-HT4-7-F2-3030-DATA-SHEET-101016

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